

## NCE N-Channel Enhancement Mode Power MOSFET

### Description

The NCE70H10F uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.

### General Features

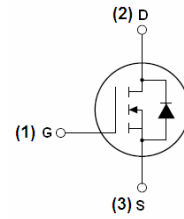
- $V_{DS} = 70V, I_D = 100A$   
 $R_{DS(ON)} < 5.5 m\Omega @ V_{GS} = 10V$  (Typ: 4.8mΩ)
- High density cell design for ultra low  $R_{DS(ON)}$
- Fully characterized avalanche voltage and current
- Special designed for converters and power controls
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

### Application

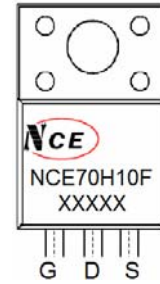
- Power switching application
- Hard switched and High frequency circuits
- Uninterruptible power supply

**100% UIS TESTED!**

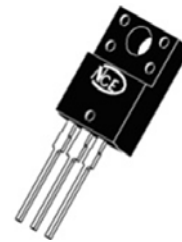
**100%  $\Delta V_{DS}$  TESTED!**



Schematic diagram



Marking and pin assignment



TO-220F top view

### Package Marking and Ordering Information

| Device Marking | Device    | Device Package | Reel Size | Tape width | Quantity |
|----------------|-----------|----------------|-----------|------------|----------|
| NCE70H10F      | NCE70H10F | TO-220F        | -         | -          | -        |

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ unless otherwise noted)

| Parameter   | Symbol             | Limit      | Unit          |
|---|--------------------|------------|---------------|
| Drain-Source Voltage                              | $V_{DS}$           | 70         | V             |
| Gate-Source Voltage                               | $V_{GS}$           | $\pm 20$   | V             |
| Drain Current-Continuous                          | $I_D$              | 100        | A             |
| Drain Current-Continuous( $T_C = 100^\circ C$ )   | $I_D(100^\circ C)$ | 70.7       | A             |
| Pulsed Drain Current                              | $I_{DM}$           | 320        | A             |
| Maximum Power Dissipation                         | $P_D$              | 45         | W             |
| Derating factor                                   |                    | 0.3        | W/ $^\circ C$ |
| Single pulse avalanche energy <sup>(Note 5)</sup> | $E_{AS}$           | 812        | mJ            |
| Operating Junction and Storage Temperature Range  | $T_J, T_{STG}$     | -55 To 175 | $^\circ C$    |

### Thermal Characteristic

|  |                 |     |              |
|--|-----------------|-----|--------------|
| Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup> | $R_{\theta JC}$ | 3.3 | $^\circ C/W$ |
|--|-----------------|-----|--------------|

## Electrical Characteristics ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

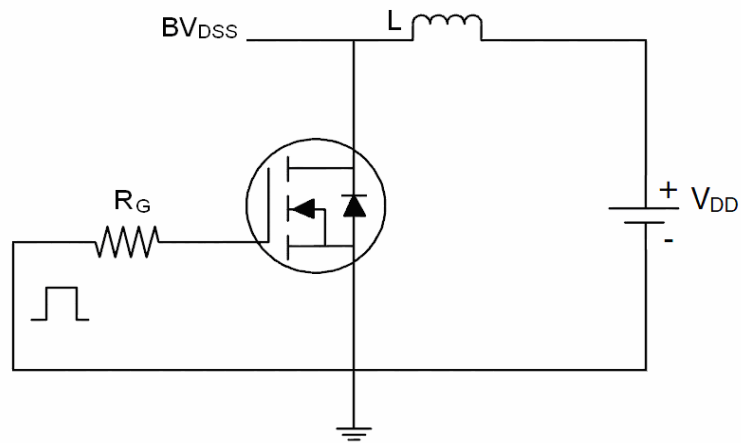
| Parameter                                     | Symbol              | Condition   | Min | Typ  | Max  | Unit |
|---|---------------------|---|-----|------|------|------|
| Off Characteristics                           |                     |   |     |      |      |      |
| Drain-Source Breakdown Voltage                | BV <sub>DSS</sub>   | V <sub>GS</sub> =0V I <sub>D</sub> =250μA                                     | 70  | -    | -    | V    |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>    | V <sub>DS</sub> =70V, V <sub>GS</sub> =0V                                     | -   | -    | 1    | μA   |
| Gate-Body Leakage Current                     | I <sub>GSS</sub>    | V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V                                    | -   | -    | ±100 | nA   |
| On Characteristics <sup>(Note 3)</sup>        |                     |   |     |      |      |      |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub> | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA                      | 2   | 2.85 | 4    | V    |
| Drain-Source On-State Resistance              | R <sub>DS(ON)</sub> | V <sub>GS</sub> =10V, I <sub>D</sub> =20A                                     | -   | 4.8  | 5.5  | mΩ   |
| Forward Transconductance                      | g <sub>FS</sub>     | V <sub>DS</sub> =5V, I <sub>D</sub> =20A                                      | -   | 50   | -    | S    |
| Dynamic Characteristics <sup>(Note4)</sup>    |                     |   |     |      |      |      |
| Input Capacitance                             | C <sub>iss</sub>    | V <sub>DS</sub> =25V, V <sub>GS</sub> =0V,<br>F=1.0MHz                        | -   | 4900 | -    | PF   |
| Output Capacitance                            | C <sub>oss</sub>    |   | -   | 380  | -    | PF   |
| Reverse Transfer Capacitance                  | C <sub>rss</sub>    |   | -   | 290  | -    | PF   |
| Switching Characteristics <sup>(Note 4)</sup> |                     |   |     |      |      |      |
| Turn-on Delay Time                            | t <sub>d(on)</sub>  | VDD=35V, RL=15Ω<br>RG=2.5Ω, VGS=10V   | -   | 17   | -    | nS   |
| Turn-on Rise Time                             | t <sub>r</sub>      |   | -   | 11   | -    | nS   |
| Turn-Off Delay Time                           | t <sub>d(off)</sub> |   | -   | 55   | -    | nS   |
| Turn-Off Fall Time                            | t <sub>f</sub>      |   | -   | 15   | -    | nS   |
| Total Gate Charge                             | Q <sub>g</sub>      | V <sub>DS</sub> =35V, I <sub>D</sub> =20A,<br>V <sub>GS</sub> =10V            | -   | 100  | -    | nC   |
| Gate-Source Charge                            | Q <sub>gs</sub>     |   | -   | 21   | -    | nC   |
| Gate-Drain Charge                             | Q <sub>gd</sub>     |   | -   | 30   | -    | nC   |
| Drain-Source Diode Characteristics            |                     |   |     |      |      |      |
| Diode Forward Voltage <sup>(Note 3)</sup>     | V <sub>SD</sub>     | V <sub>GS</sub> =0V, I <sub>S</sub> =20A                                      | -   | -    | 1.2  | V    |
| Diode Forward Current <sup>(Note 2)</sup>     | I <sub>S</sub>      |   | -   | -    | 100  | A    |
| Reverse Recovery Time                         | t <sub>rr</sub>     | T <sub>j</sub> =25℃, I <sub>F</sub> =100A<br>di/dt=100A/μs <sup>(Note3)</sup> | -   |      | 37   | nS   |
| Reverse Recovery Charge                       | Q <sub>rr</sub>     |   | -   |      | 58   | nC   |
| Forward Turn-On Time                          | t <sub>on</sub>     | Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)          |     |      |      |      |

### Notes:

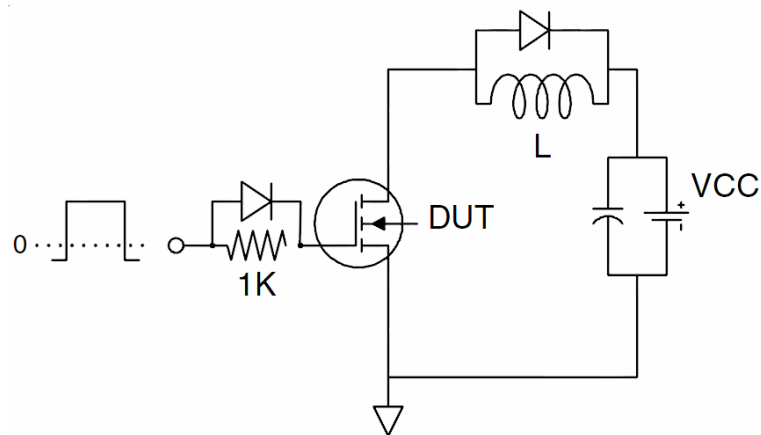
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5. EAS condition:  $T_J=25^{\circ}\text{C}, V_{DD}=35V, V_G=10V, L=0.5mH, R_g=25\Omega$

## Test Circuit

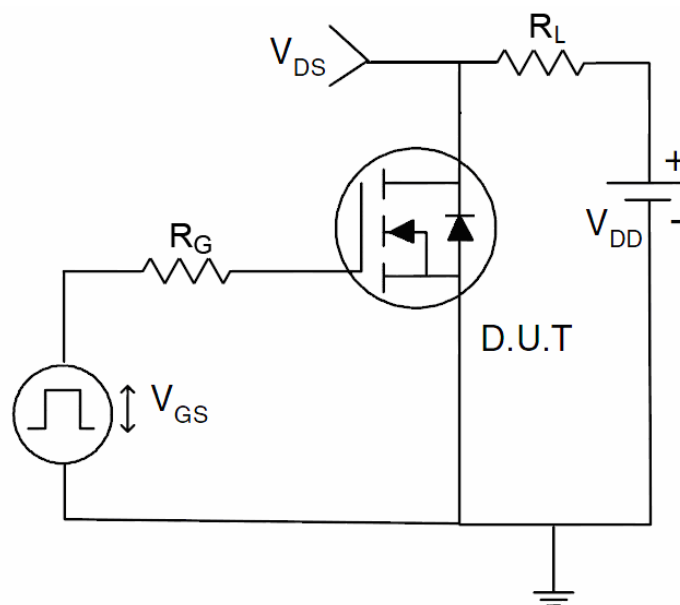
### 1) $E_{AS}$ Test Circuits



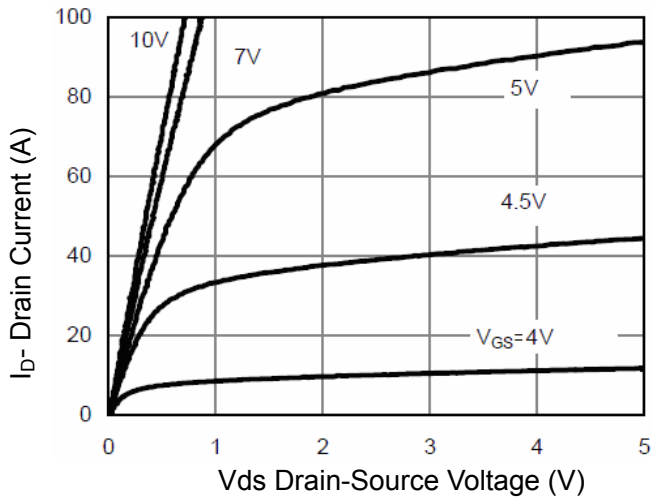
### 2) Gate Charge Test Circuit



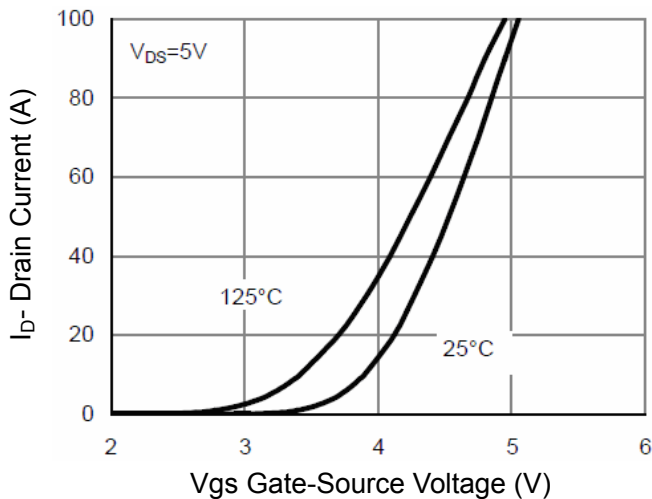
### 3) Switch Time Test Circuit



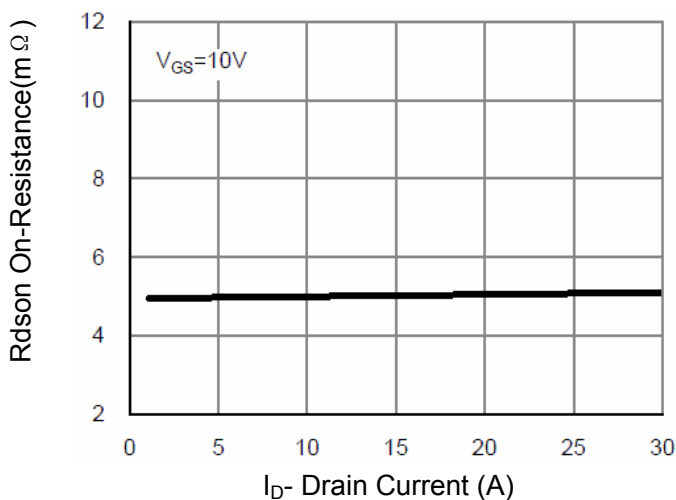
## Typical Electrical and Thermal Characteristics (Curves)



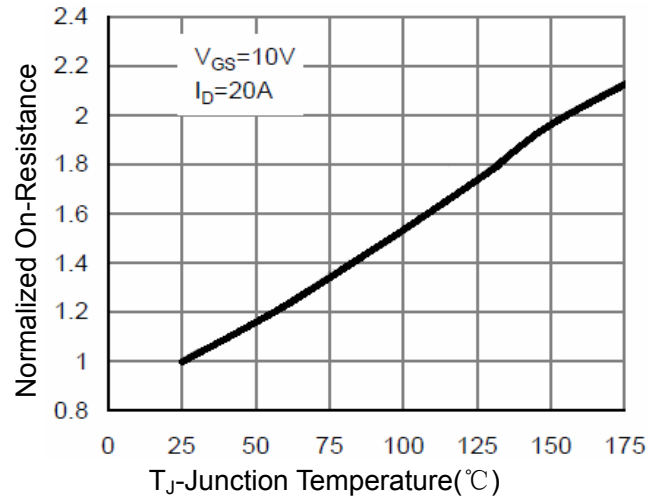
**Figure 1 Output Characteristics**



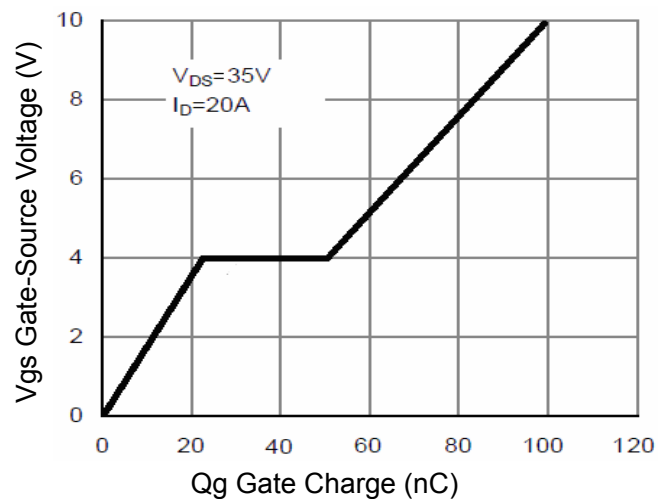
**Figure 2 Transfer Characteristics**



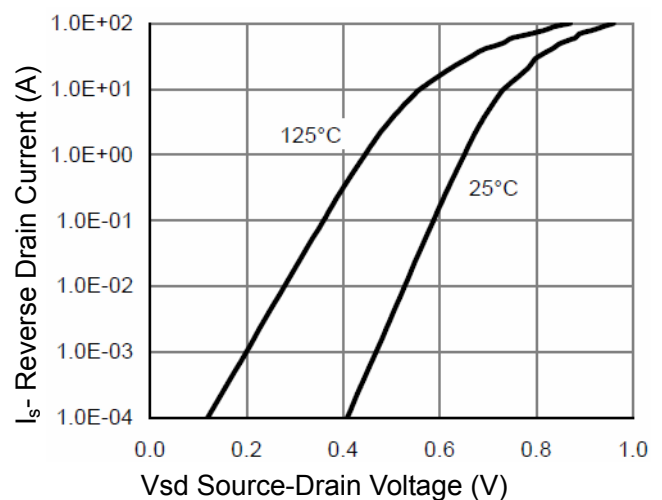
**Figure 3  $R_{DS(on)}$ - Drain Current**



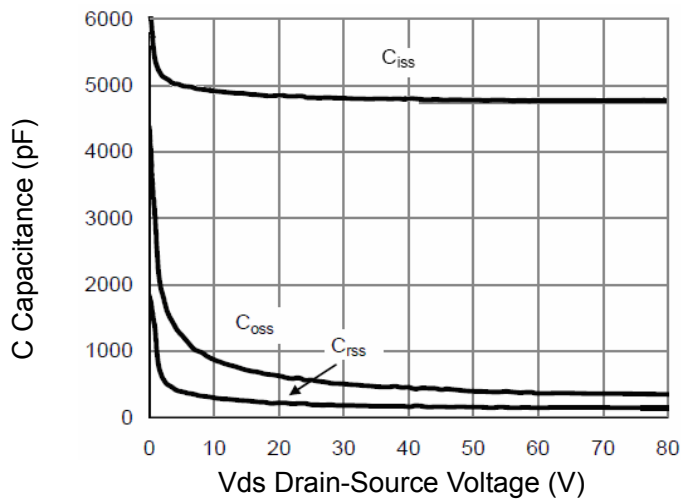
**Figure 4  $R_{DS(on)}$ -Junction Temperature**



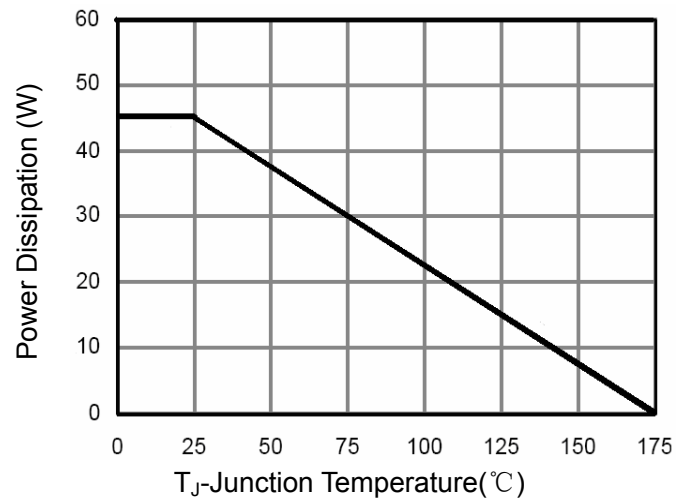
**Figure 5 Gate Charge**



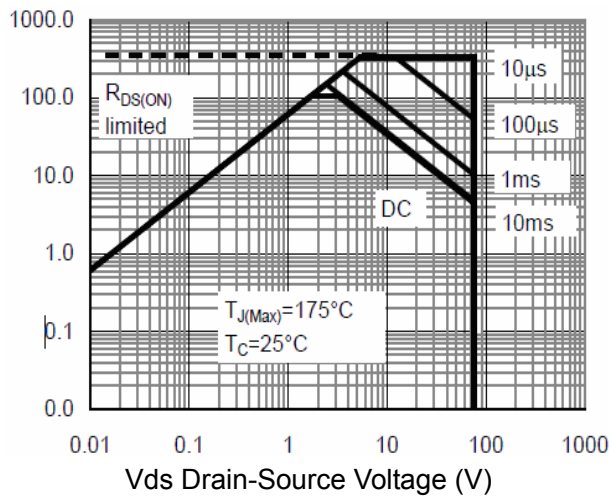
**Figure 6 Source- Drain Diode Forward**



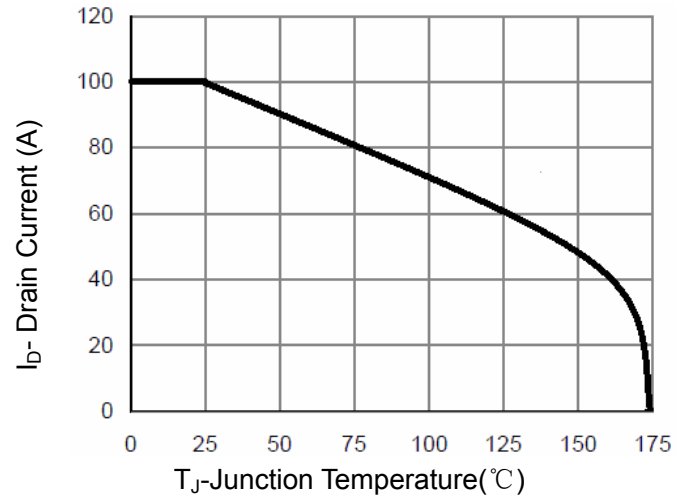
**Figure 7 Capacitance vs Vds**



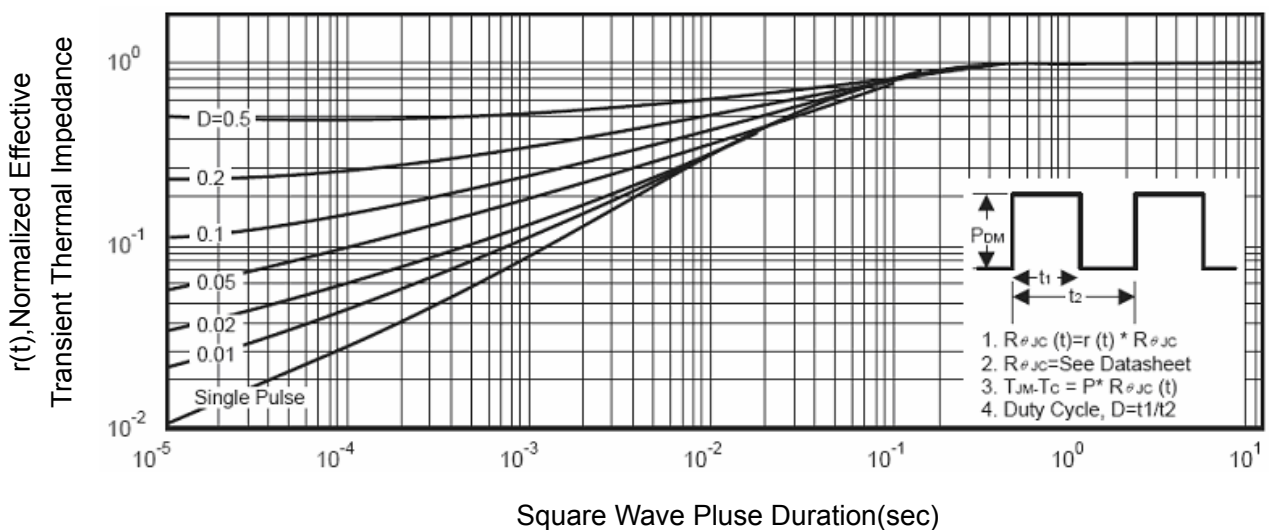
**Figure 9 Power De-rating**



**Figure 8 Safe Operation Area**

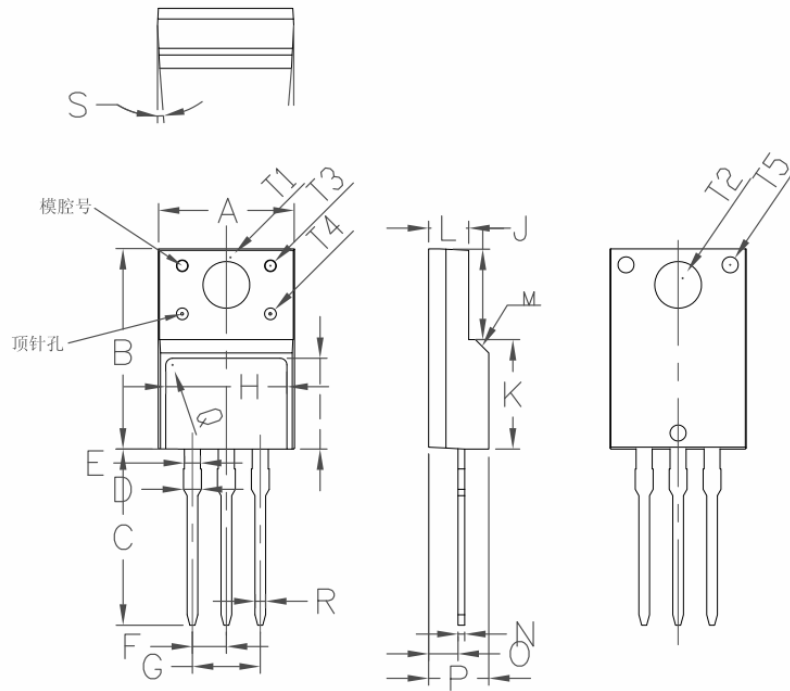


**Figure 10 ID Current De-rating**



**Figure 11 Normalized Maximum Transient Thermal Impedance**

## TO-220FPackage Information



| Symbol | Min   | Non   | Max   |
|--------|-------|-------|-------|
| A      | 9.96  | 10.16 | 10.36 |
| B      | 15.67 | 15.87 | 16.07 |
| C      | 13.14 | 13.34 | 13.54 |
| D      | 1.20  | 1.30  | 1.40  |
| E      |       | 1.20  |       |
| F      |       | 2.54  |       |
| G      |       | 5.08  |       |
| H      | 7.60  | 7.80  | 8.00  |
| I      | 7.10  | 7.30  | 7.50  |
| J      | 6.48  | 6.68  | 6.88  |
| K      | 8.99  | 9.19  | 9.39  |
| L      | 2.34  | 2.54  | 2.74  |
| M      |       | 45°   |       |
| N      | 0.49  | 0.50  | 0.52  |
| O      | 2.15  | 2.35  | 2.55  |
| P      | 4.50  | 4.70  | 4.90  |
| Q      |       | 0.50  |       |
| S      | 4°    | 4.5°  | 5°    |
| T1     |       | 3.45  |       |
| T2     |       | 3.18  |       |
| T3     |       | 1.50  |       |
| T4     |       | 1.20  |       |
| T5     |       | 1.50  |       |
| R      | 0.77  | 0.8   | 0.83  |

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